

10-01-01
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September 27, 2001

Attorney Docket No.: MP0115

Box Patent Application
Commissioner for Patents
Washington, DC 20231

Presented for filing is a new original patent application of:

Applicant: SEHAT SUTARDJA

Title: IMPROVED INTEGRATED CHIP PACKAGE HAVING
INTERMEDIATE SUBSTRATE

Enclosed are the following papers, including those required to receive a filing date
under 37 CFR §1.53(b):

	Pages
Specification	11
Claims	7
Abstract	1
Declaration	2
Drawing(s)	3

Enclosures:

- Assignment cover sheet and an assignment, 2 pages, and a separate \$40 fee.
- Assignment cover sheet and an assignment, 3 pages, and a separate \$40 fee.
- Request and Certification under 35 USC 122(b)(2)(B)(i).
- New disclosure information, including: Information disclosure statement, 1 page, PTO-1449, 1 page, and References, 15 items.
- Postcard.

CERTIFICATE OF MAILING BY EXPRESS MAIL

Express Mail Label No. EL870690834US

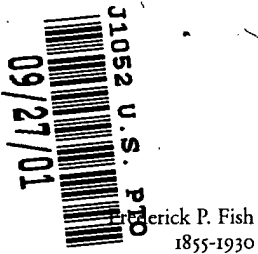
I hereby certify under 37 CFR §1.10 that this correspondence is being deposited with the United States Postal Service as Express Mail Post Office to Addressee with sufficient postage on the date indicated below and is addressed to the Commissioner for Patents, Washington, D.C. 20231.

Date of Deposit September 27, 2001

Signature

Michael Hubbard

Typed or Printed Name of Person Signing Certificate



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Basic filing fee	\$710
Total claims in excess of 20 times \$9	\$144
Independent claims in excess of 3 times \$40	\$0
Fee for multiple dependent claims	\$0
Total filing fee:	\$854

A check for the filing fee is enclosed. Please apply any other required fees or any credits to deposit account 06-1050, referencing the attorney docket number shown above.

If this application is found to be incomplete, or if a telephone conference would otherwise be helpful, please call the undersigned at (858) 678-5070.

Kindly acknowledge receipt of this application by returning the enclosed postcard.

Please send all correspondence to:

ERIC B. JANOFFSY
Marvel Semiconductor, Inc.
645 Almanor Ave.
Sunnyvale, CO 94086

Respectfully submitted,



Joseph L. Stevenson
Reg. No. 43163
Enclosures
JLS/krc
10136736.doc

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Inventor: Sutardja, Sehat

Group Art Unit: Not Yet
Assigned

Serial No.: Not Yet Assigned

Examiner: Not Yet Assigned

Filed: Herewith

Title: Improved Integrated Chip Package Having Intermediate Substrate

**REQUEST AND CERTIFICATION
UNDER 35 U.S.C. 122(b)(2)(B)(i)**Commissioner for Patents
Washington, D.C. 20231

Sir:

I hereby certify that the invention disclosed in the attached application **has not been and is not intended, at this time, to be the subject of an application filed in another country, or under a multilateral agreement, that requires publication at eighteen months after filing.**

I hereby request that the attached application not be published under 35 U.S.C. 122(b).

Applicant reserves the right to subsequently file an application directed to the invention disclosed in the attached application in another country, or under a multilateral international agreement, that requires publication of applications eighteen months after filing. At that time, Applicant intends to notify the United

States Patent and Trademark Office of such filing within forty-five (45) days after the date of the filing of such foreign or international application.

Respectfully submitted,



Eric B. Janofsky
Attorney for Applicant
Registration No. 30,759

Date:

9/26/2001

10/26/01 14:39:00